



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	20-01-2025
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST33KTPM2X32DKJ1	U4MG*G4ADKJ1	A	993N	20-01-2025
	Amount	UoM	Unit type	ST ECOPACK Grade
	46.88	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Matte Tin	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
EQFN	5x5x0.55mm	32		
Comment	Package : A0B8 UFQFPN 5X5X0.55 32L 0.5 MM PITCH 8202208			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2024				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	U4MG*G4ADK1				5999999.0	1007127.8
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	0.609	mg	supplier	die	Silicon (Si)	7440-21-3		0.456	mg	748768	9728
				supplier	metallization	Aluminium (Al)	7429-90-5		0.018	mg	29557	384
				supplier	metallization	Copper (Cu)	7440-50-8		0.057	mg	93596	1216
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.009	mg	14778	192
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	3284	43
				supplier	Passivation	Silicon Oxide	7631-86-9		0.067	mg	110016	1429
Leadframe-C7025-Ag	Copper & its alloys	20.100	mg	supplier	Alloy	Cu	7440-50-8		19.246	mg	957500	410576
					Alloy	Ni	7440-02-0		0.599	mg	29800	12778
					Alloy	Si	7440-21-3		0.131	mg	6500	2787
					Alloy	Mg	7439-95-4		0.030	mg	1500	643
					coating	Ag	7440-22-4		0.094	mg	4700	2015
Glue - 8600	M-011 Other inorganic materials	0.763	mg	supplier	Glue	Silver	7440-22-4		0.622	mg	815000	13272
					Glue	[Octahydro-4,7-methano-1H-indenediy]bis(m	42594-17-2		0.046	mg	60000	977
					Glue	exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl met	7534-94-3		0.046	mg	60000	977
					Glue	Isobornyl acrylate	5888-33-5		0.046	mg	60000	977
					Glue	2-(3,4-Epoxy cyclohexyl)ethyltrimethoxysilane	3388-04-3		0.004	mg	5000	81
Bonding wire- AuPdCu wire	M-011 Other inorganic materials	0.740	mg	supplier	Bonding wire	Copper	7440-50-8		0.714	mg	965000	15432
					Bonding wire	Palladium	7440-05-3		0.018	mg	24990	400
					Bonding wire	Gold	7440-57-5		0.007	mg	10000	160
					Bonding wire	Silver	7440-22-4		0.000	mg	10	0
Encapsulation - EME-G700LTD	M-011 Other inorganic materials	22.872	mg	supplier	Molding compound	Epoxy Resin	Proprietary		1.144	mg	50000	24719
					Molding compound	Phenol Resin	Proprietary		0.618	mg	27000	13348
					Molding compound	Silica (Amorphous)A	60676-86-0		19.899	mg	870000	430106
					Molding compound	Silica (Amorphous)B	7631-86-9		1.144	mg	50000	24719
					Molding compound	Carbon Black	1333-86-4		0.069	mg	3000	1483
External plating - Matte Tin	M-011 Other inorganic materials	1.790	mg	supplier	Matte tin	Tin	7440-31-5		1.790	mg	1000000	38685